

Accepted Manuscript

The Effect of Liquidity and Solvency Risk on the Inclusion of Bond Covenants

Douglas O. Cook, Xudong Fu, Tian Tang

PII: S0378-4266(14)00251-9

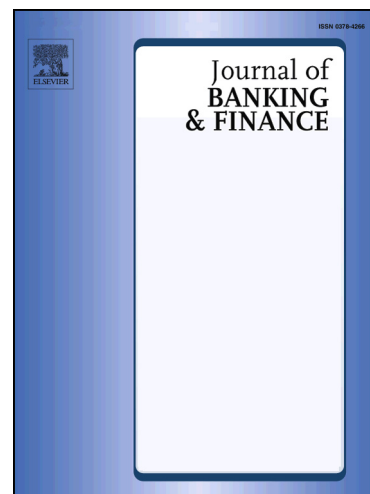
DOI: <http://dx.doi.org/10.1016/j.jbankfin.2014.07.004>

Reference: JBF 4517

To appear in: *Journal of Banking & Finance*

Received Date: 31 July 2013

Accepted Date: 5 July 2014



Please cite this article as: Cook, D.O., Fu, X., Tang, T., The Effect of Liquidity and Solvency Risk on the Inclusion of Bond Covenants, *Journal of Banking & Finance* (2014), doi: <http://dx.doi.org/10.1016/j.jbankfin.2014.07.004>

This is a PDF file of an unedited manuscript that has been accepted for publication. As a service to our customers we are providing this early version of the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting proof before it is published in its final form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain.

The Effect of Liquidity and Solvency Risk on the Inclusion of Bond Covenants

Douglas O. Cook
Department of Economics, Finance & Legal Studies
University of Alabama
Tuscaloosa, AL 35487
205-348-8971
dcook@cba.ua.edu

Xudong Fu
Department of Economics and Finance
Southern Illinois University Edwardsville
Edwardsville, IL 62026
618- 650-5195
xfu@siue.edu

Tian Tang
Department of Finance
University of Louisville
Louisville, KY 40292
502 - 852 - 4819
lori.tang@louisville.edu

Download English Version:

<https://daneshyari.com/en/article/5088782>

Download Persian Version:

<https://daneshyari.com/article/5088782>

[Daneshyari.com](https://daneshyari.com)